PMP9104 REVB BOM

| Designator | Qty | Value | Description | Package | PartNumber | Mfg |
|--------------------------------------|-----|---------------|---|----------------|--------------------------|-------------|
| C1 | 1 | 100uF | CAP, AL, 100uF, 100V, +/-20%, TH | 10x20 | 100ZL100MEFC10X20 | Rubycon |
| C2, C3, C4, C5 | 4 | 4.7uF | CAP, CERM, 4.7uF, 100V, +/-20%, X7S, 1210 | 1210 | C3225X7S2A475M200AB | TDK |
| C6 | 1 | 10uF | CAP, CERM, 10uF, 50V, +/-20%, X7R, 1210 | 1210 | C3225X7R1H106M250AC | TDK |
| C8, C9, C10 | 3 | 39uF | CAP, OS-CON, 39uF, 50V, +/-20%, 0.025 ohm, 8x10 SMD | 8x10 | 50SVPF39M | Sanyo |
| C11 | 1 | | CAP, CERM, DNP, 100V, +/-5%, C0G/NP0, 0603 | 0603 | | TDK |
| C12, C16 | 2 | 0.1uF | CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603 | 0603 | C1608X7R1H104K | TDK |
| C7, 'C13 | | 0.1uF | CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603 | 0603 | GRM188R72A104KA35D | MuRata |
| C14 | | 0.018uF | CAP, CERM, 0.018uF, 50V, +/-10%, X7R, 0603 | 0603 | C1608X8R1H183K | TDK |
| C15 | | 4.7uF | CAP, CERM, 4.7uF, 10V, +/-10%, X5R, 0603 | 0603 | CGB3B1X5R1A475K055A C | |
| C17 | 1 | 680pF | CAP, CERM, 680pF, 50V, +/-5%, C0G/NP0, 0603 | 0603 | C1608C0G1H681J | TDK |
| C18 | 1 | 1uF | CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603 | 0603 | C1608X5R1C105K | TDK |
| C19 | 1 | 47pF | CAP, CERM, 47pF, 50V, +/-5%, C0G/NP0, 0603 | 0603 | C1608C0G1H470J | TDK |
| D1, D4 | | BAT54HT1G | Diode, Schottky, 30V, 0.2A, SOD-323 | SOD-323 | BAT54HT1G | ON Semi |
| D2, D3 | 2 | SBR12U100P5 | Diode, Schottky, 100V, 12A, PowerDI5 | PowerDI5 | SBR12U100P5 | Diodes Inc. |
| J1, J2 | 2 | | Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH | 7.0x8.2x6.5mm | ED555/2DS | OST |
| L1 | 1 | 1uH | Inductor, Shielded, Powdered Iron, 1uH, 9.5A, 8 ohm, SMD | | IHLP2525CZER1R0M11 | Vishay-Dale |
| L2 | 1 | 22uH | Inductor, Shielded, Composite, 22uH, 14A, 0.0145 ohm, SMD | 15.4x11x16.4mm | XAL1510-223ME | Coilcraft |
| Q1, Q2 | 2 | BSC123N08NS3G | MOSFET, N-CH, 80V, 55A, PG-TDSON-8 | PG-TDSON-8 | BSC123N08NS3G | Infineon |
| R1 | 1 | 1.00 | RES, 1.00 ohm, 1%, 0.25W, 1206 | 1206 | CRCW12061R00FKEA | Vishay-Dale |
| R2, R3 | 2 | 10.0 | RES, 10.0 ohm, 1%, 0.1W, 0603 | 0603 | CRCW060310R0FKEA | Vishay-Dale |
| R4, R5 | 2 | DNP | RES, DNP, 1%, 0.25W, 1206 | 1206 | DNP | Vishay-Dale |
| R6, R7, R9 | 3 | 0 | RES, 0 ohm, 5%, 0.1W, 0603 | 0603 | CRCW06030000Z0EA | Vishay-Dale |
| R8 | 1 | 0.01 | RES, 0.01 ohm, 1%, 1W, 2512 | 2512 | WSL2512R0100FEA | Vishay-Dale |
| R10 | 1 | 1.00Meg | RES, 1.00Meg ohm, 1%, 0.1W, 0603 | 0603 | CRCW06031M00FKEA | Vishay-Dale |
| R11 | 1 | 301k | RES, 301k ohm, 1%, 0.1W, 0603 | 0603 | CRCW0603301KFKEA | Vishay-Dale |
| R12 | 1 | 20.0 | RES, 20.0 ohm, 1%, 0.1W, 0603 | 0603 | CRCW060320R0FKEA | Vishay-Dale |
| R13 | 1 | 22.1k | RES, 22.1k ohm, 1%, 0.1W, 0603 | 0603 | CRCW060322K1FKEA | Vishay-Dale |
| R14 | 1 | 20.0k | RES, 20.0k ohm, 1%, 0.125W, 0805 | 0805 | CRCW080520K0FKEA | Vishay-Dale |
| R15 | 1 | 18.7k | RES, 18.7k ohm, 1%, 0.1W, 0603 | 0603 | CRCW060318K7FKEA | Vishay-Dale |
| R16 | 1 | 24.9k | RES, 24.9k ohm, 1%, 0.1W, 0603 | 0603 | CRCW060324K9FKEA | Vishay-Dale |
| R17 | 1 | 1.21k | RES, 1.21k ohm, 1%, 0.1W, 0603 | 0603 | CRCW06031K21FKEA | Vishay-Dale |
| R18 | 1 | 909 | RES, 909 ohm, 1%, 0.1W, 0603 | 0603 | CRCW0603909RFKEA | Vishay-Dale |
| TP1, TP3, | 8 | Red | Test Point, TH, Miniature, Red | Keystone5000 | 5000 | Keystone |
| TP4, TP5, TP7, TP9, TP10, TP11 | | | | | | Í |
| TP2, TP6, TP8, TP12, TP13 | 5 | Black | Test Point, TH, Miniature, Black | Keystone5001 | 5001 | Keystone |
| U1 | 1 | LM5118MH | Wide Voltage Range Buck-Boost Controller, 20-pin TSSOP-EP | MXA20A | LM5118MH | TI |

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